

FMH28N50E

FUJI POWER MOSFET

Super FAP-E³ series

N-CHANNEL SILICON POWER MOSFET

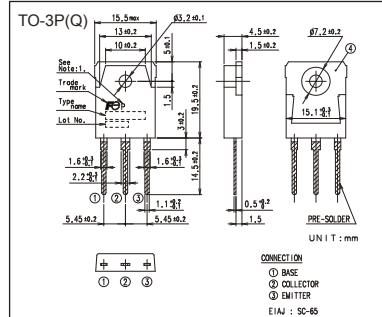
■ Features

- Maintains both low power loss and low noise
- Lower $R_{DS(on)}$ characteristic
- More controllable switching dv/dt by gate resistance
- Smaller V_{GS} ringing waveform during switching
- Narrow band of the gate threshold voltage ($3.0 \pm 0.5V$)
- High avalanche durability

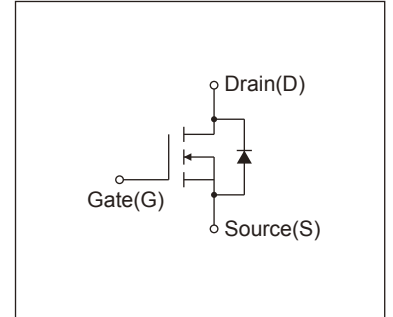
■ Applications

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

■ Outline Drawings [mm]



■ Equivalent circuit schematic



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings at $T_c=25^\circ\text{C}$ (unless otherwise specified)

| Description | Symbol | Characteristics | Unit | Remarks |
|---|-----------|-----------------|-------------------|------------------------|
| Drain-Source Voltage | V_{DS} | 500 | V | |
| | V_{DSX} | 500 | V | $V_{GS} = -30V$ |
| Continuous Drain Current | I_D | ± 28 | A | |
| Pulsed Drain Current | I_{DP} | ± 112 | A | |
| Gate-Source Voltage | V_{GS} | ± 30 | V | |
| Repetitive and Non-Repetitive Maximum Avalanche Current | I_{AR} | 28 | A | Note*1 |
| Non-Repetitive Maximum Avalanche Energy | E_{AS} | 1033.1 | mJ | Note*2 |
| Repetitive Maximum Avalanche Energy | E_{AR} | 40 | mJ | Note*3 |
| Peak Diode Recovery dV/dt | dV/dt | 10.9 | kV/ μs | Note*4 |
| Peak Diode Recovery $-di/dt$ | $-di/dt$ | 100 | A/ μs | Note*5 |
| Maximum Power Dissipation | P_D | 2.50 | W | $T_a=25^\circ\text{C}$ |
| | | 400 | | $T_c=25^\circ\text{C}$ |
| Operating and Storage Temperature range | T_{ch} | 150 | $^\circ\text{C}$ | |
| | T_{slg} | -55 to + 150 | $^\circ\text{C}$ | |

● Electrical Characteristics at $T_c=25^\circ\text{C}$ (unless otherwise specified)

| Description | Symbol | Conditions | min. | typ. | max. | Unit |
|----------------------------------|--------------|---|------|------|------|---------------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $I_D=250\mu\text{A}$, $V_{GS}=0V$ | 500 | - | - | V |
| Gate Threshold Voltage | $V_{GS(th)}$ | $I_D=250\mu\text{A}$, $V_{DS}=V_{GS}$ | 2.5 | 3.0 | 3.5 | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=500V$, $V_{GS}=0V$ | - | - | 25 | μA |
| | | $V_{DS}=400V$, $V_{GS}=0V$ | - | - | 250 | |
| Gate-Source Leakage Current | I_{GSS} | $V_{GS}=\pm 30V$, $V_{DS}=0V$ | - | 10 | 100 | nA |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $I_D=14A$, $V_{GS}=10V$ | - | 0.16 | 0.19 | Ω |
| Forward Transconductance | g_{fs} | $I_D=14A$, $V_{DS}=25V$ | 16 | 32 | - | S |
| Input Capacitance | C_{iss} | $V_{DS}=25V$ | - | 4400 | 6600 | pF |
| Output Capacitance | C_{oss} | $V_{GS}=0V$ | - | 420 | 630 | |
| Reverse Transfer Capacitance | C_{rss} | $f=1\text{MHz}$ | - | 32 | 48 | ns |
| Turn-On Time | $t_d(on)$ | $V_{cc}=300V$ | - | 26 | 39 | |
| | t_r | $V_{GS}=10V$ | - | 14 | 21 | |
| Turn-Off Time | $t_d(off)$ | $I_D=14A$ | - | 144 | 216 | |
| | t_f | $R_{GS}=5.1\Omega$ | - | 24 | 36 | |
| Total Gate Charge | Q_G | $V_{cc}=250V$ | - | 130 | 195 | nC |
| Gate-Source Charge | Q_{GS} | $I_D=28A$ | - | 30 | 45 | |
| Gate-Drain Charge | Q_{GD} | $V_{GS}=10V$ | - | 40 | 60 | |
| Avalanche Capability | I_{AV} | $L=1.04\text{mH}$, $T_{ch}=25^\circ\text{C}$ | 28 | - | - | A |
| Diode Forward On-Voltage | V_{SD} | $I_F=28A$, $V_{GS}=0V$, $T_{ch}=25^\circ\text{C}$ | - | 0.90 | 1.35 | V |
| Reverse Recovery Time | t_{rr} | $I_F=28A$, $V_{GS}=0V$ | - | 0.72 | - | μs |
| Reverse Recovery Charge | Q_{rr} | $-di/dt=100A/\mu\text{s}$, $T_{ch}=25^\circ\text{C}$ | - | 11.2 | - | μC |

● Thermal Characteristics

| Description | Symbol | Test Conditions | min. | typ. | max. | Unit |
|--------------------|----------------|--------------------|------|------|-------|--------------------|
| Thermal resistance | $R_{th(ch-c)}$ | Channel to Case | | | 0.313 | $^\circ\text{C/W}$ |
| | $R_{th(ch-a)}$ | Channel to Ambient | | | 50.0 | $^\circ\text{C/W}$ |

Note *1 : $T_{ch} \leq 150^\circ\text{C}$

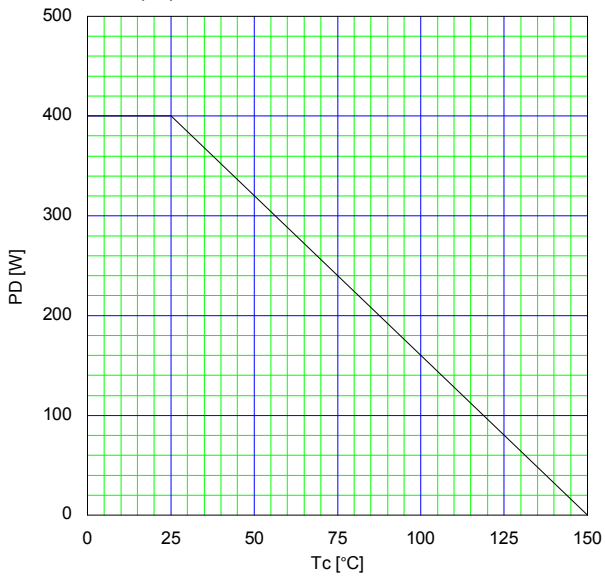
Note *2 : Stating $T_{ch}=25^\circ\text{C}$, $I_{AS}=12A$, $L=13.2\text{mH}$, $V_{cc}=50V$, $R_G=50\Omega$
 E_{AS} limited by maximum channel temperature and avalanche current.
 See to 'Avalanche Energy' graph.

Note *3 : Repetitive rating : Pulse width limited by maximum channel temperature.
 See to the 'Transient Thermal Impedance' graph.

Note *4 : $I_F \leq I_D$, $-di/dt=100A/\mu\text{s}$, $V_{cc} \leq BV_{DSS}$, $T_{ch} \leq 150^\circ\text{C}$.

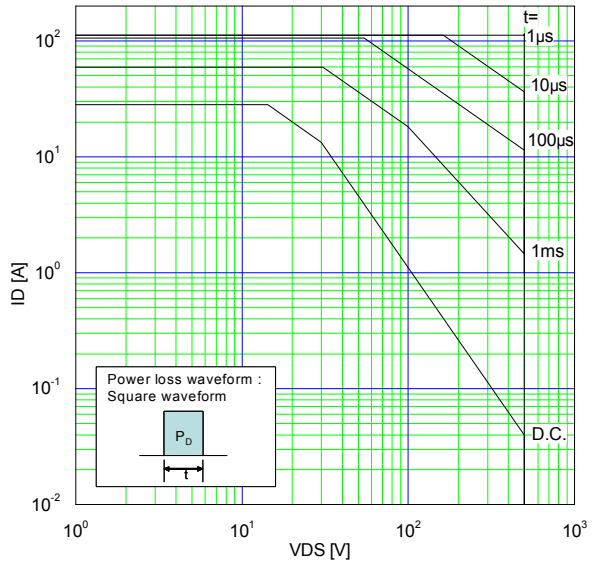
Note *5 : $I_F \leq I_D$, $dv/dt=10.9\text{kV}/\mu\text{s}$, $V_{cc} \leq BV_{DSS}$, $T_{ch} \leq 150^\circ\text{C}$.

Allowable Power Dissipation
 $PD=f(T_c)$

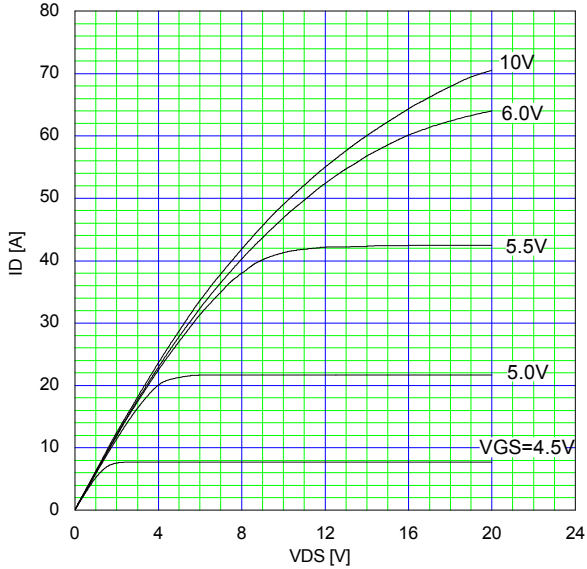


Safe Operating Area

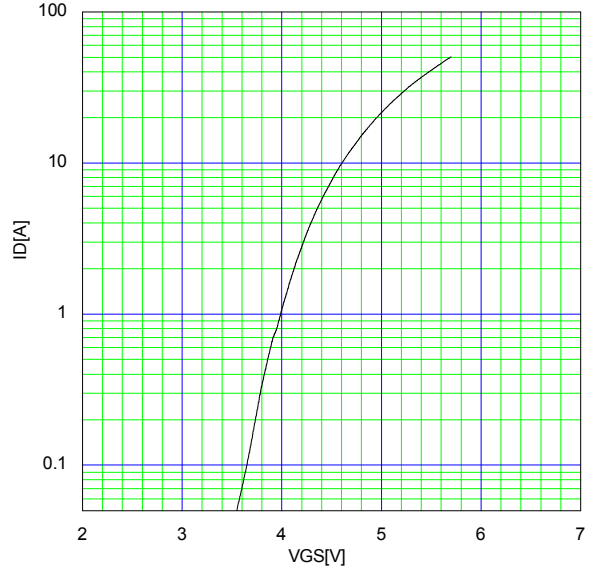
$I_D=f(V_{DS}): Duty=0(\text{Single pulse}), T_c=25^{\circ}C$



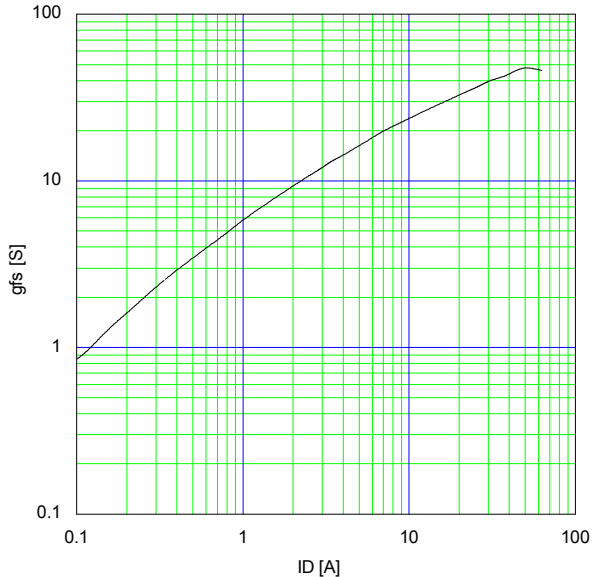
Typical Output Characteristics
 $I_D=f(V_{DS}): 80 \mu s \text{ pulse test}, T_{ch}=25^{\circ}C$



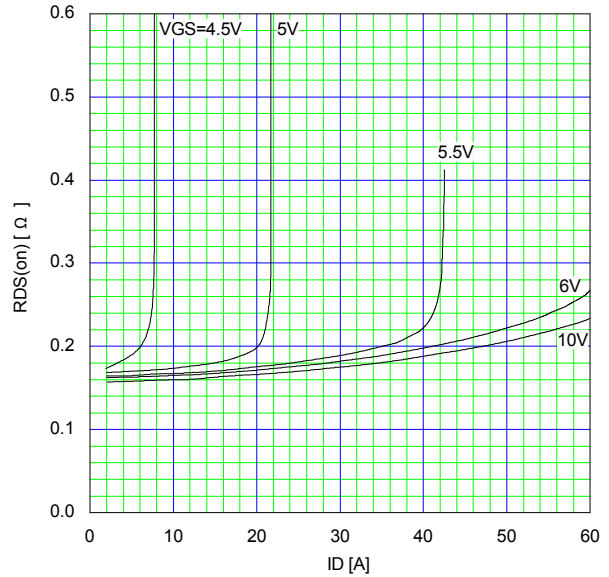
Typical Transfer Characteristic
 $I_D=f(V_{GS}): 80 \mu s \text{ pulse test}, V_{DS}=25V, T_{ch}=25^{\circ}C$



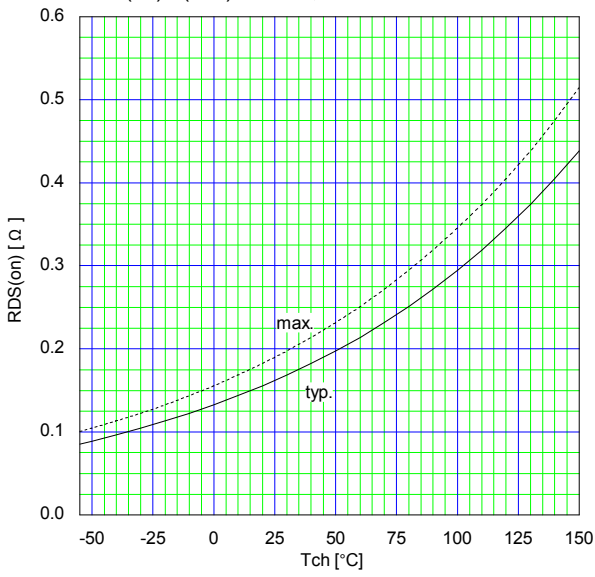
Typical Transconductance
 $g_{fs}=f(I_D): 80 \mu s \text{ pulse test}, V_{DS}=25V, T_{ch}=25^{\circ}C$



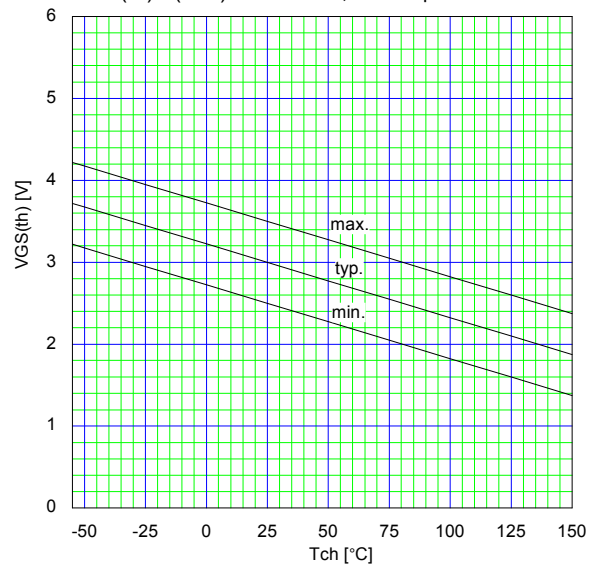
Typical Drain-Source on-state Resistance
 $R_{DS(on)}=f(I_D): 80 \mu s \text{ pulse test}, T_{ch}=25^{\circ}C$



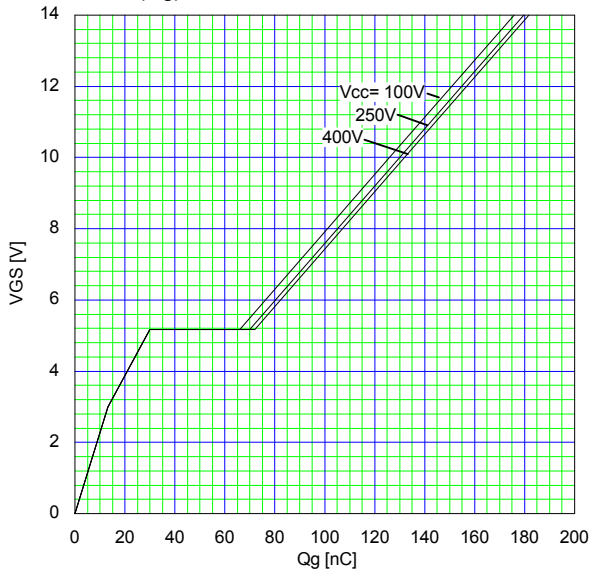
Drain-Source On-state Resistance
 $R_{DS(on)} = f(T_{ch}) : I_D = 14A, V_{GS} = 10V$



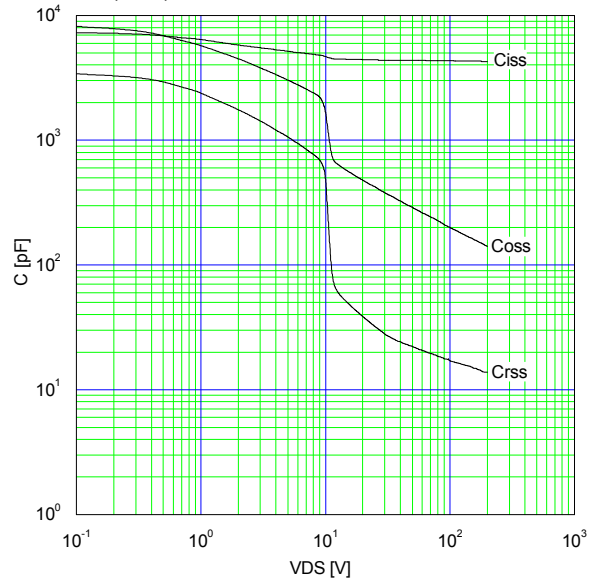
Gate Threshold Voltage vs. T_{ch}
 $V_{GS(th)} = f(T_{ch}) : V_{DS} = V_{GS}, I_D = 250\mu A$



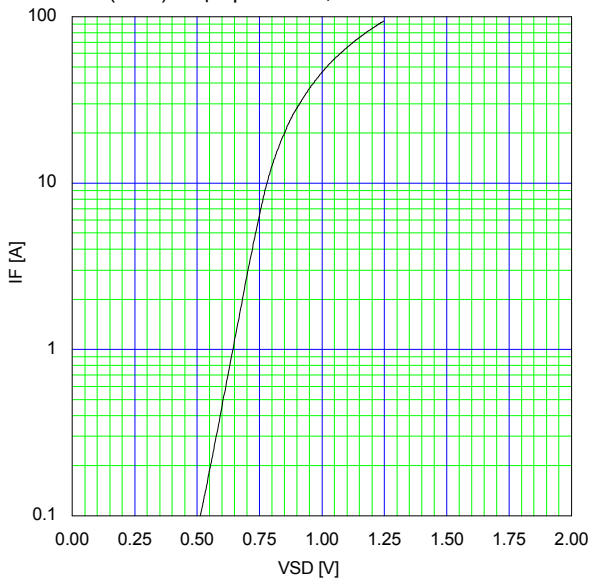
Typical Gate Charge Characteristics
 $V_{GS} = f(Q_g) : I_D = 28A, T_{ch} = 25\text{ °C}$



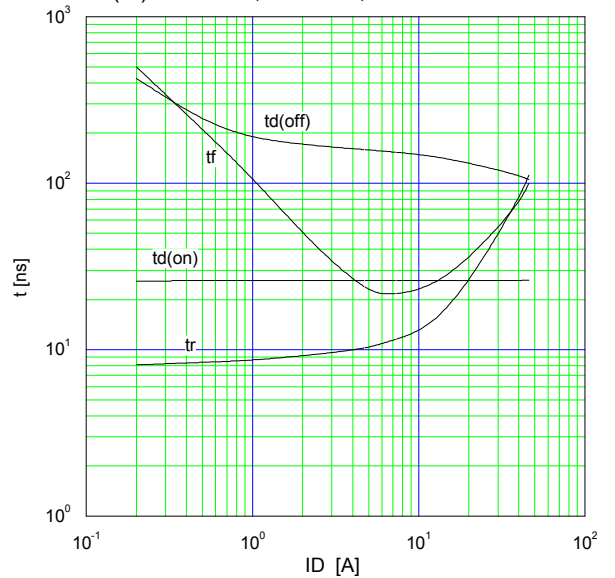
Typical Capacitance
 $C = f(V_{DS}) : V_{GS} = 0V, f = 1MHz$



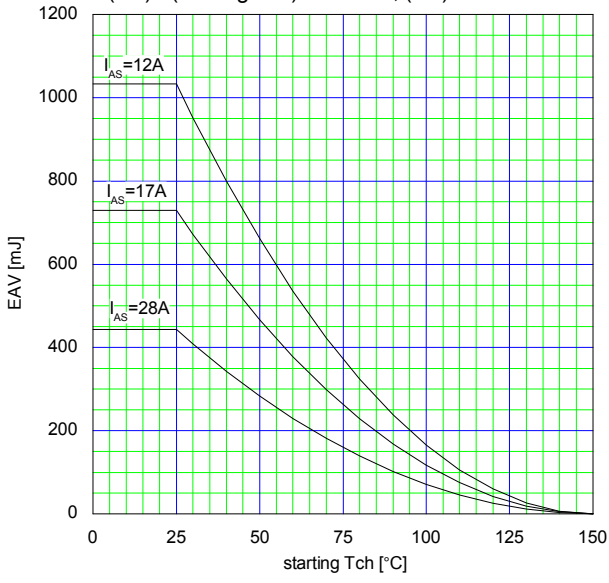
Typical Forward Characteristics of Reverse Diode
 $I_F = f(V_{SD}) : 80\text{ }\mu s\text{ pulse test}, T_{ch} = 25\text{ °C}$



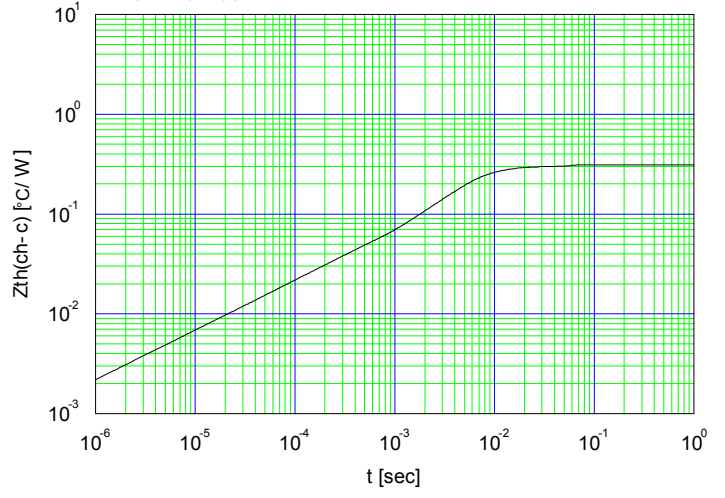
Typical Switching Characteristics vs. ID
 $t = f(I_D) : V_{cc} = 300V, V_{GS} = 10V, R_G = 5.1\text{ }\Omega$



Maximum Avalanche Energy vs. starting Tch
 $E(AV)=f(\text{starting Tch}):V_{cc}=50V, I(AV)\leq 28A$



Transient Thermal Impedance
 $Z_{th}(ch-c)=f(t):D=0$



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